

PREVIOUS CUI DEVICES DETAIL / IMAGE

NEW CUI DEVICES DETAIL / IMAGE

	MATERIAL	PLATING
terminal 1	copper alloy	gold
terminal 2	copper alloy	gold
terminal 3	copper alloy	gold
terminal 4	copper alloy	gold
terminal 5	brass	gold
terminal 6	brass	gold
plastic	PA8T or equivalent	

DESCRIPTION	MATERIAL	PLATING/COLOR
terminal 1	C5191 t~0.25	gold flash
terminal 2	C5191 t~0.20	gold flash
terminal 3	C5191 t~0.20	gold flash
terminal 4	C5191 t~0.30	gold flash
terminal 5	C2680 t~0.30	gold flash
terminal 6	C2680 t~0.30	gold flash
housing	PA8T (UL94V-0)	black

SPECIFICATIONS

parameter	conditions/description	min	typ	max	units
rated input voltage			12		Vdc
rated input current				1	A
contact resistance ¹	between terminal and mating plug between terminal in a closed circuit			50	mΩ
insulation resistance	at 500 Vdc	100			MΩ
voltage withstand	for 1 minute			500	Vac
insertion/withdrawal force		0.3		3	kg
operating temperature		-25		85	°C
life	at a rate of 24 cycles/minute		5,000		cycles
flammability rating	UL94V-0				
RoHS	yes				

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flammability rating	UL94V-0				
RoHS	yes				

SOLDERABILITY

parameter	conditions/description	min	typ	max	units
reel storage	at relative humidity <60%		40		°C
reflow soldering	see reflow profile	255	260	265	°C
drying conditions ²	parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 42°C ±5°C for 10 hours				

Note: 1. Must reflow solder within 10 hours from opening vacuum packaging at a temperature <10°C & relative humidity <60%.
2. When ascending from dry to 100% humidity.

Reflow profile graph showing Temperature (°C) vs Time (sec). The profile starts at 120°C, ramps up to 255°C, holds for 10 minutes, ramps up to 260°C, holds for 10 minutes, ramps up to 265°C, holds for 10 minutes, and then cools down.

SOLDERABILITY

parameter	conditions/description	min	typ	max	units
reel storage	5-25°C, 20-75% humidity				
reflow soldering	see reflow profile	255	260		°C

Note: 1. CUI Devices recommends usage of the product within 24 hours after TSM is opened. After 24 hours, CUI Devices recommends drying the parts prior to use.

Reflow profile graph showing Temperature (°C) vs Time (sec). The profile starts at 120°C, ramps up to 255°C, holds for 10 minutes, ramps up to 260°C, holds for 10 minutes, ramps up to 265°C, holds for 10 minutes, and then cools down. The graph also shows a peak temperature of 265°C and a cooling rate of 10°C/min.

Affected Date Code: **09/27/2023**

Product Availability: *Pertaining to market availability*

PCN Approval:

Operations/Quality



Product Management



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Revision: A